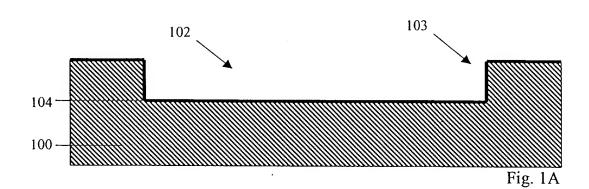
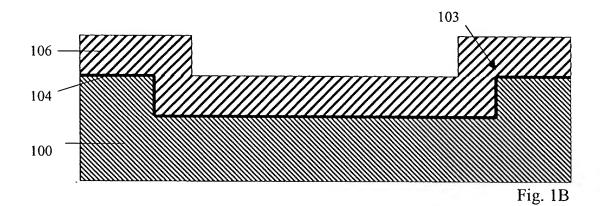
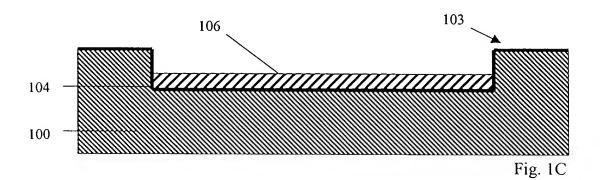
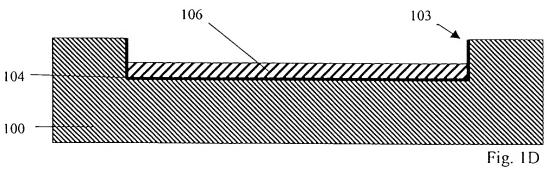
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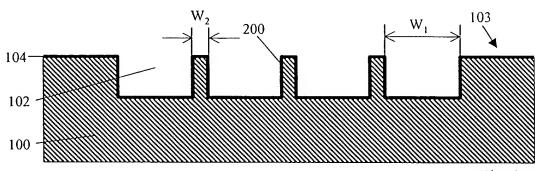


Fig. 2A

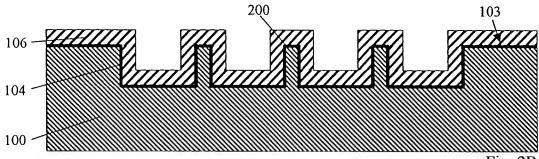
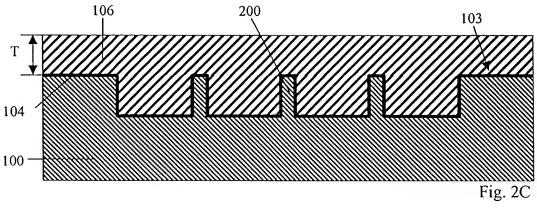


Fig. 2B



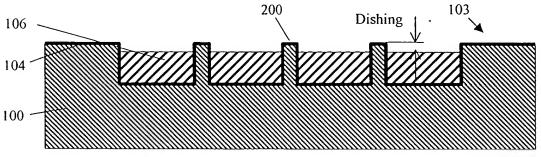
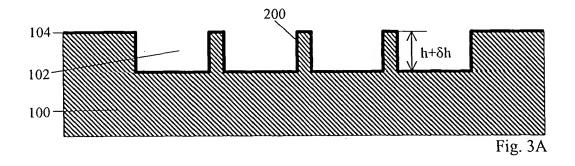
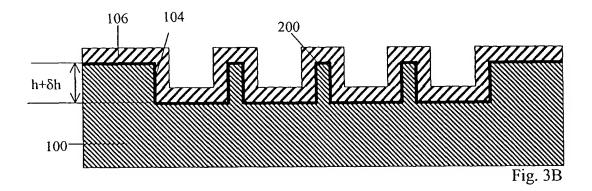


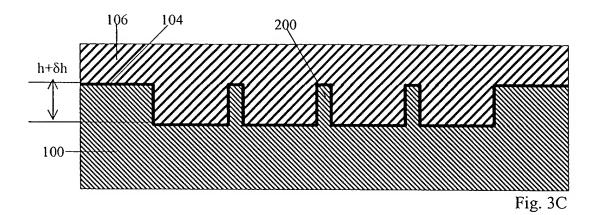
Fig. 2D

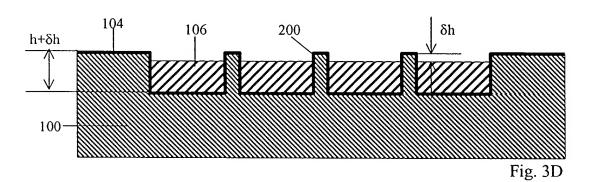
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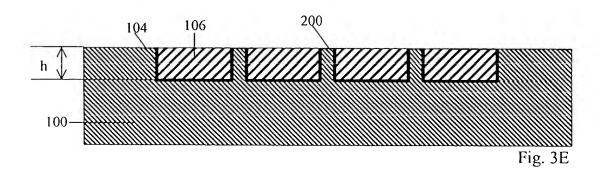




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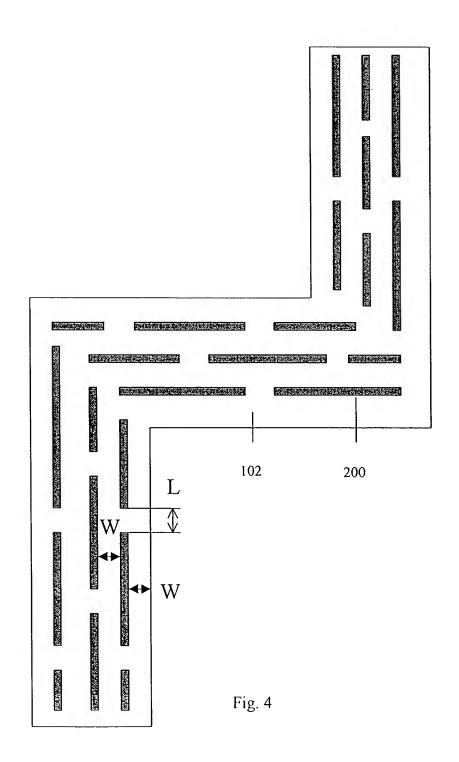




Title: ELECTROPOLISHING METAL LAYERS ON WAFERS HAVING TRENCHES OR VIAS WITH DUMMY STRUCTURES

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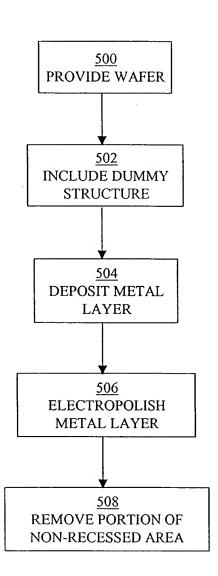


Fig. 5

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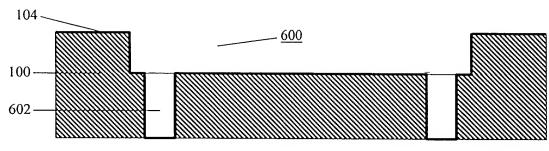


Fig. 6A

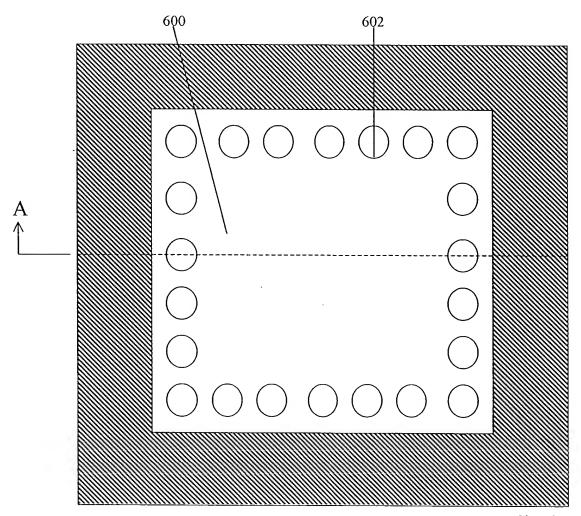
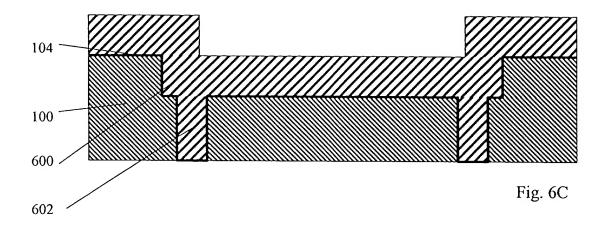
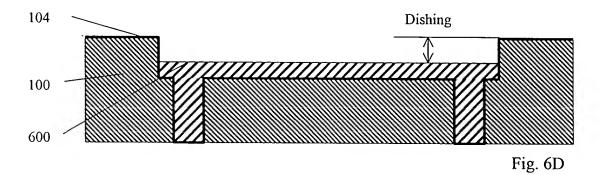
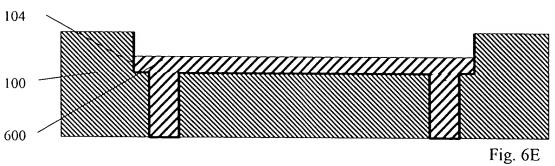


Fig. 6B

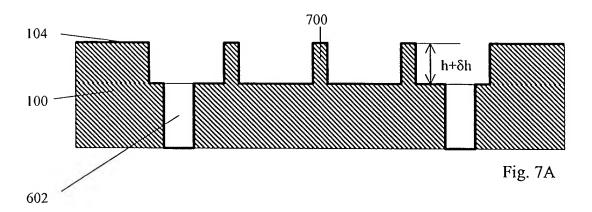


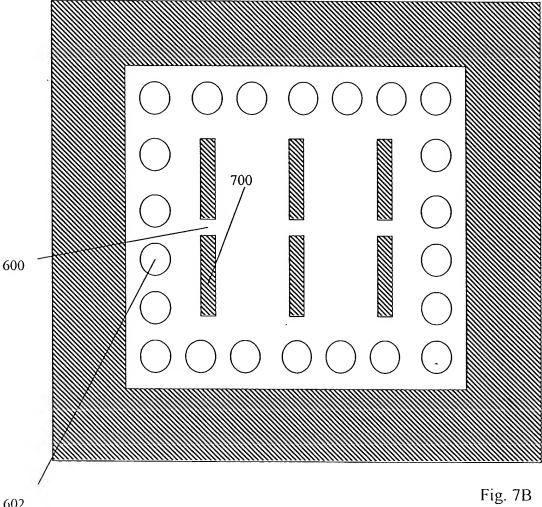




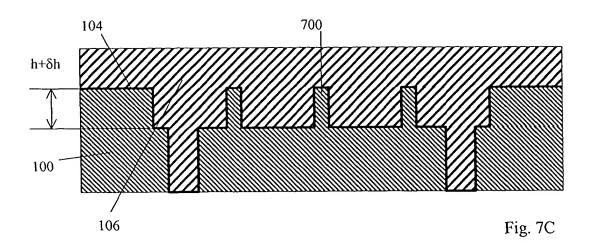


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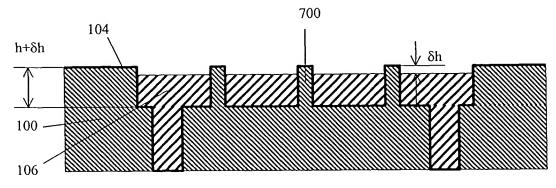


Fig. 7D

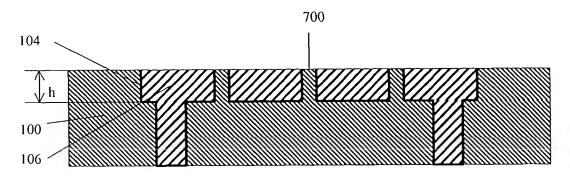
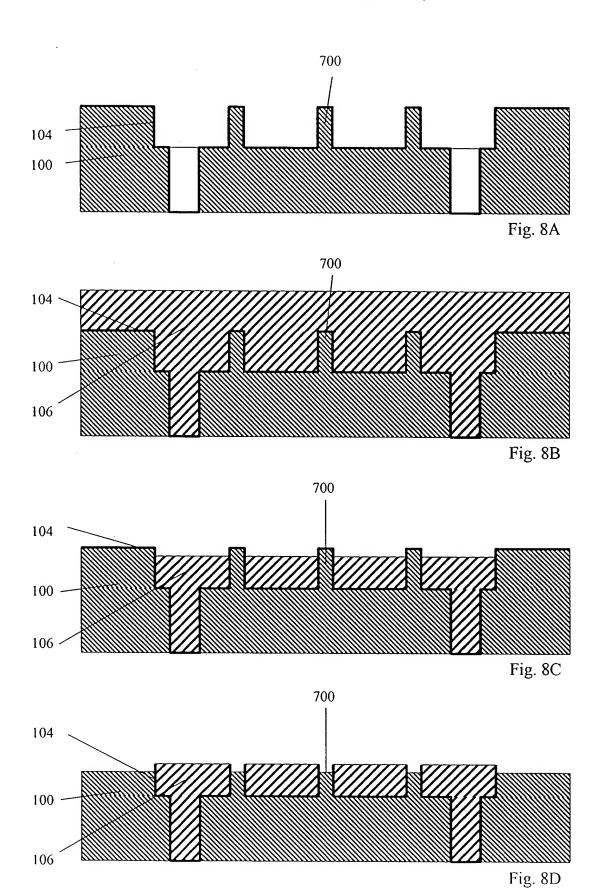


Fig. 7E

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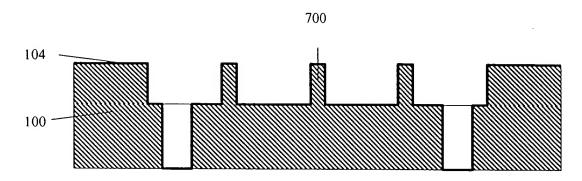
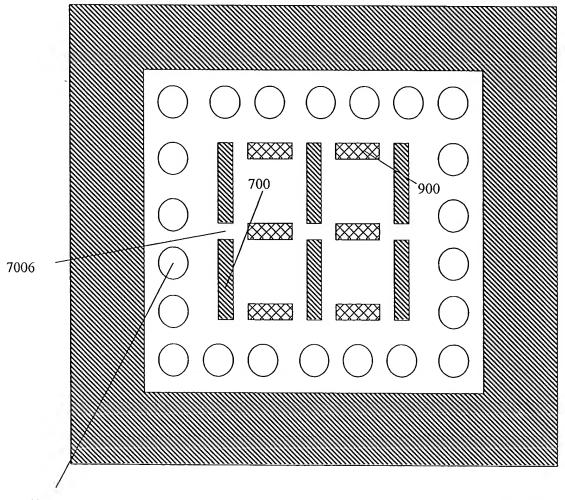
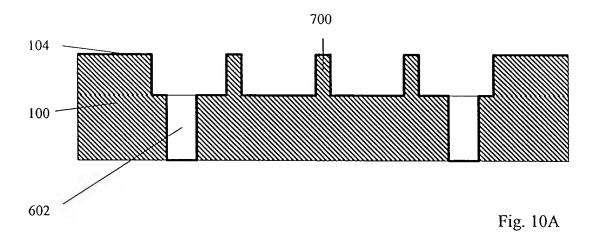


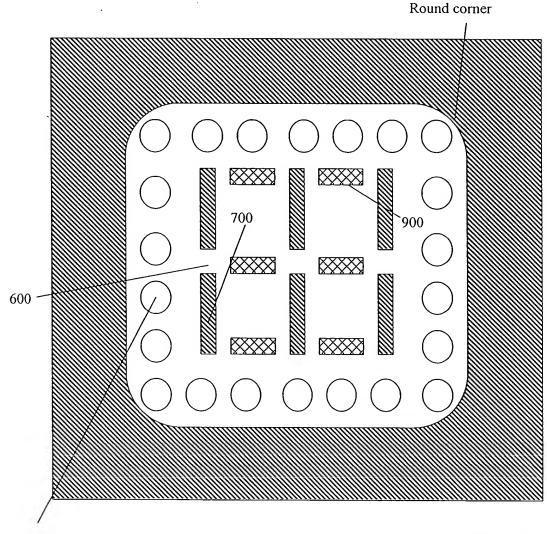
Fig. 9A



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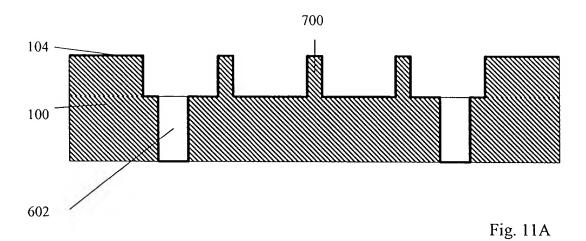


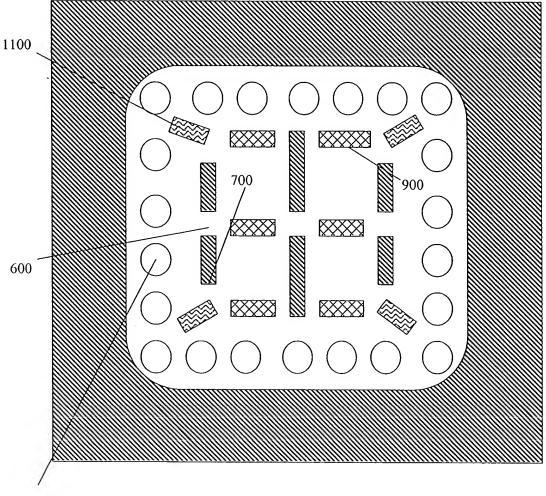


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Fig. 10B

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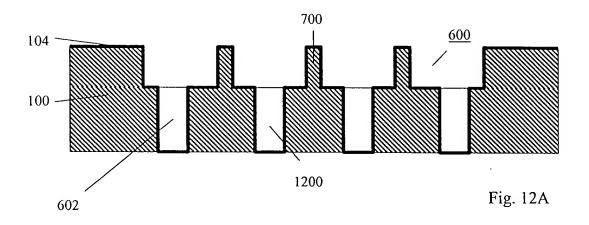
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Fig. 11B

Title: ELECTROPOLISHING METAL LAYERS ON WAFERS HAVING TRENCHES OR VIAS WITH DUMMY STRUCTURES

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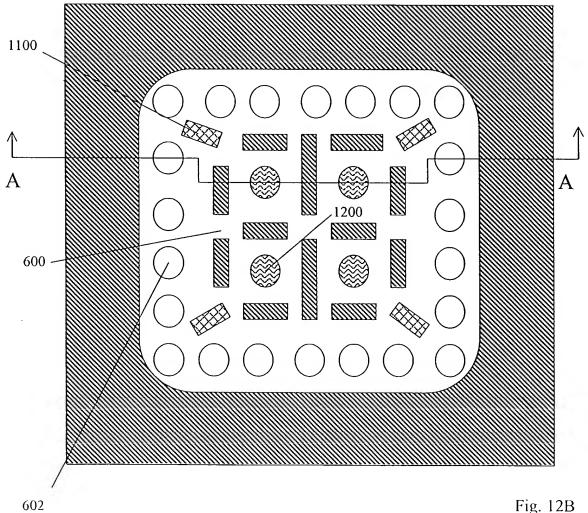


Fig. 12B

Title: ELECTROPOLISHING METAL LAYERS ON WAFERS HAVING TRENCHES OR VIAS WITH DUMMY STRUCTURES Inventor: Hui WANG and Peihaur YIH

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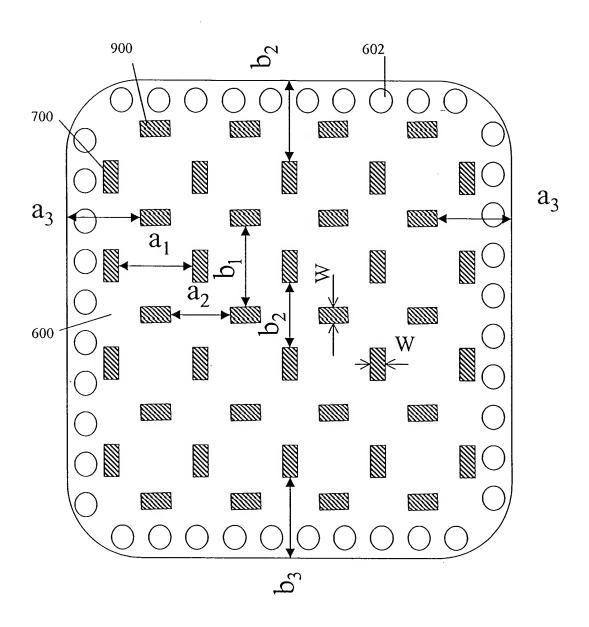


Fig. 13

Title: ELECTROPOLISHING METAL LAYERS ON WAFERS HAVING TRENCHES OR VIAS WITH DUMMY STRUCTURES

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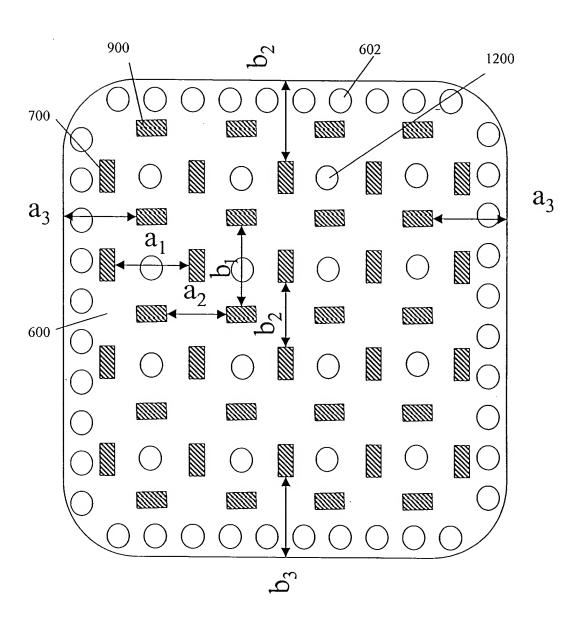


Fig. 14

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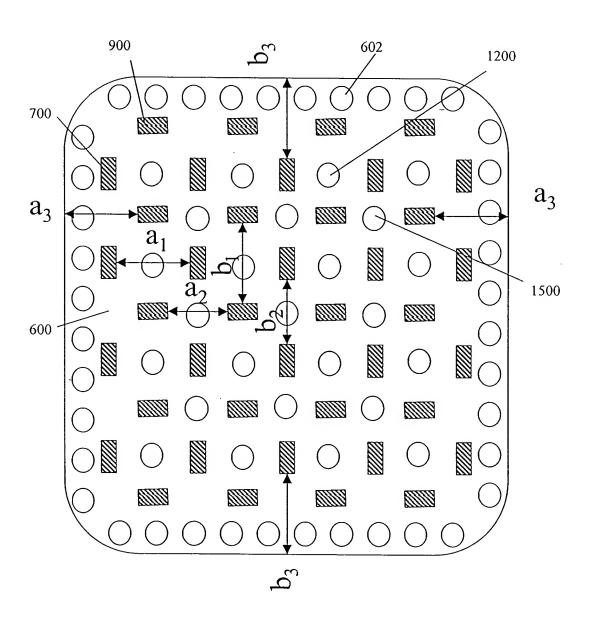


Fig. 15

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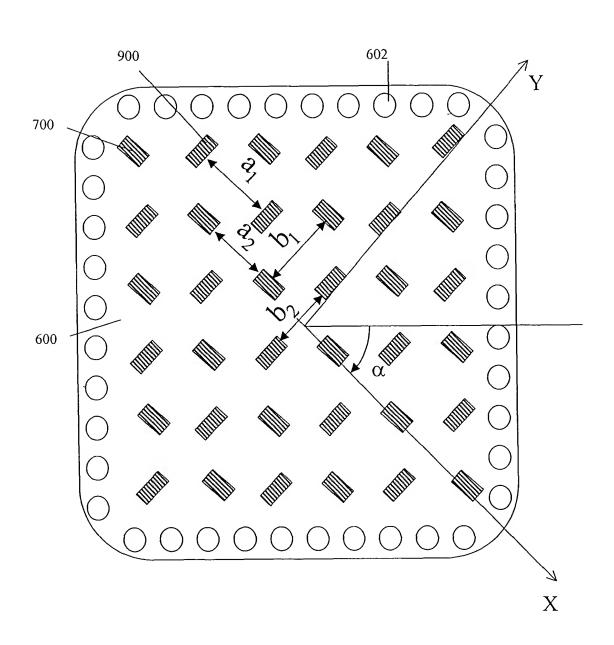
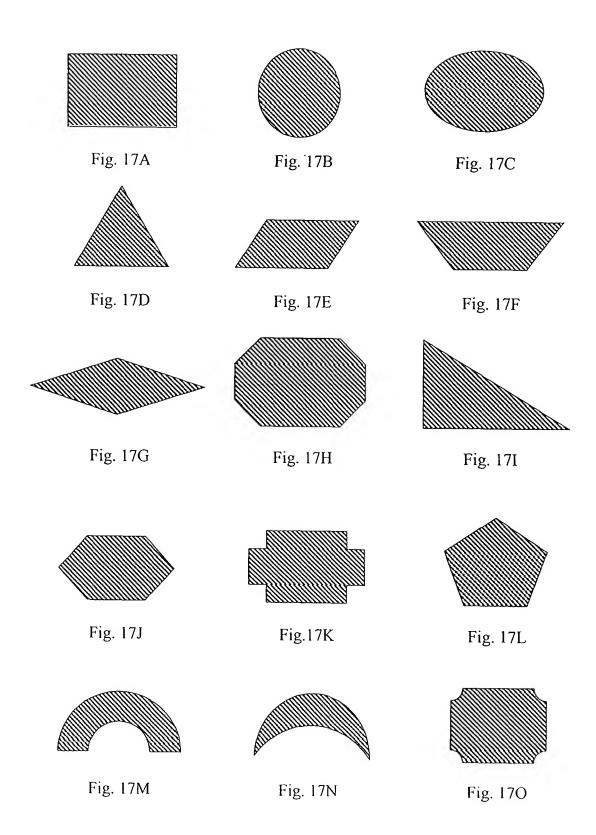
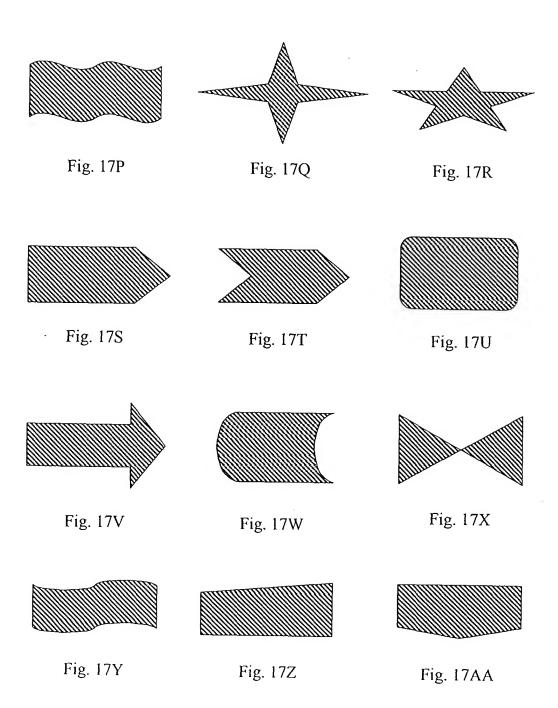


Fig. 16

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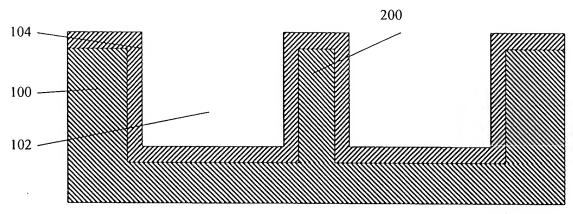


Fig.18A

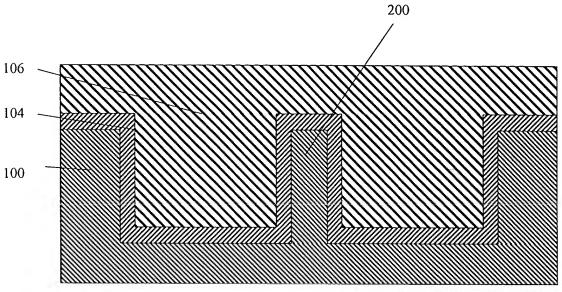


Fig.18B

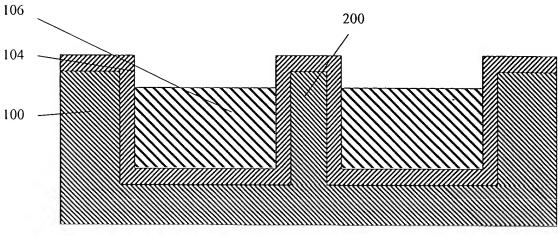


Fig.18C

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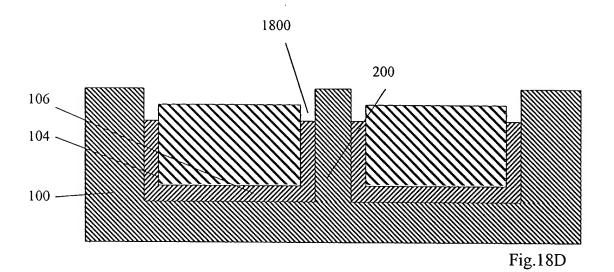


Fig.18E

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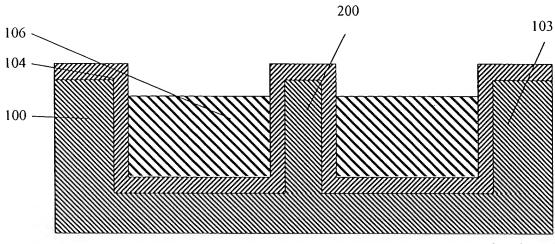


Fig.19A

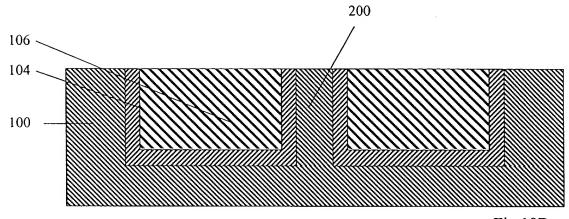


Fig.19B

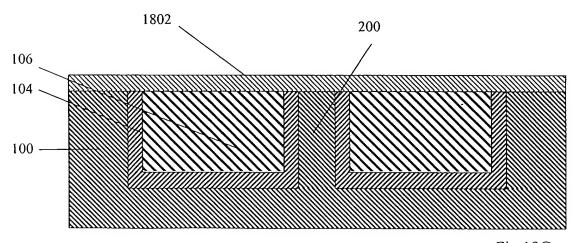


Fig.19C

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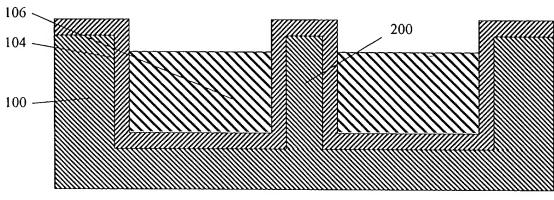


Fig.20A

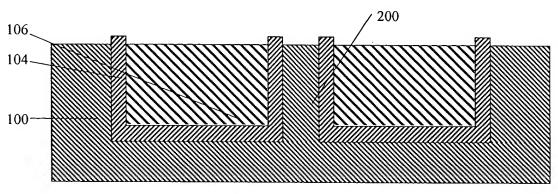


Fig.20B

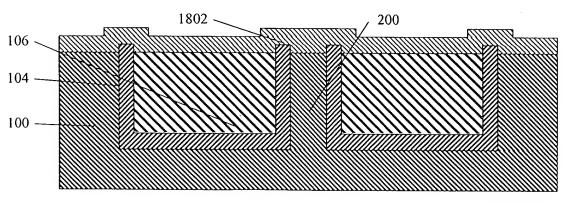
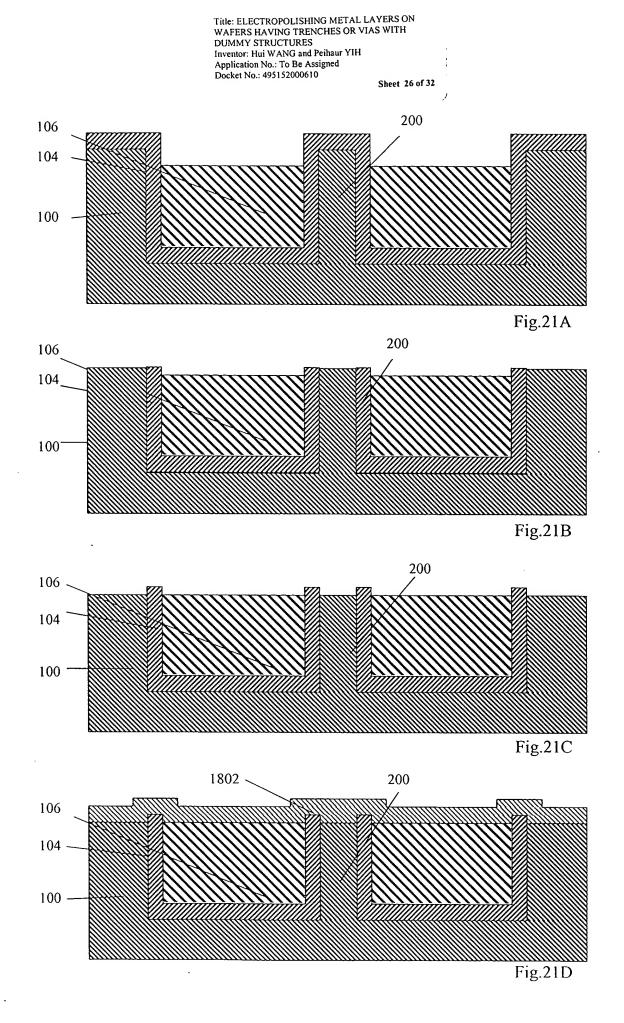


Fig.20C



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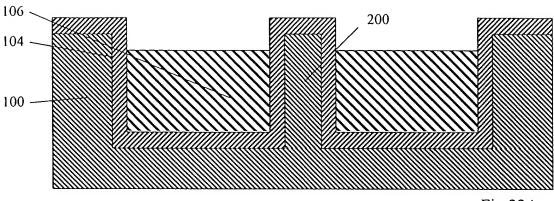


Fig.22A

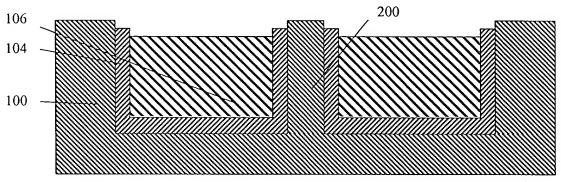


Fig.22B

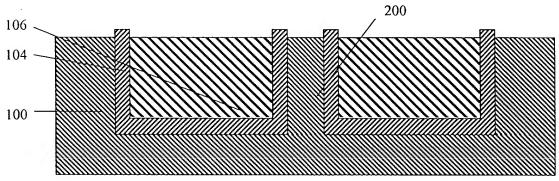


Fig.22C

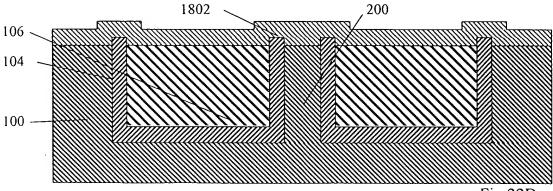
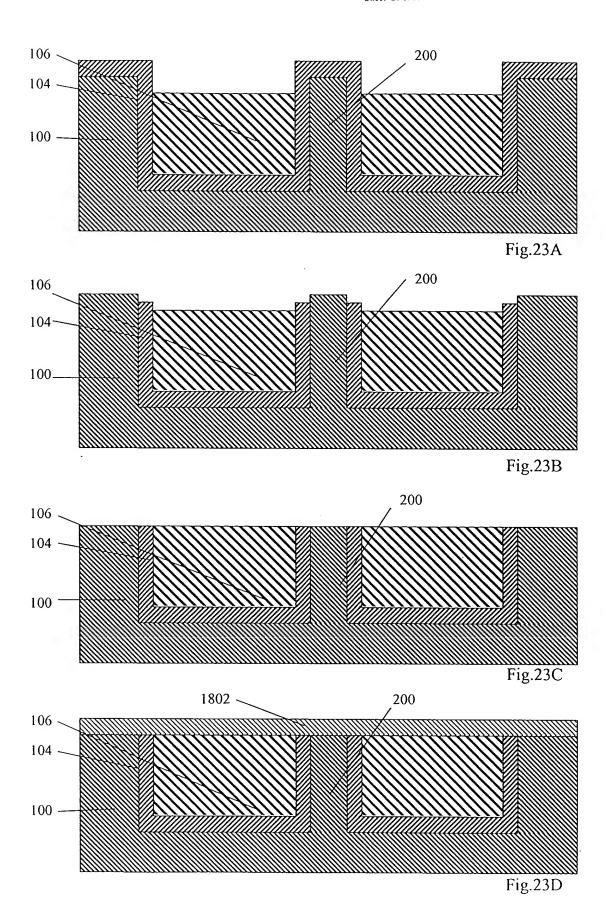


Fig.22D

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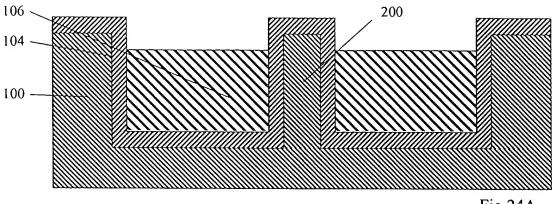


Fig.24A

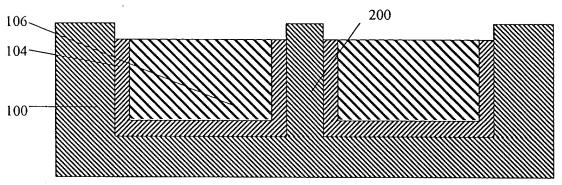


Fig.24B

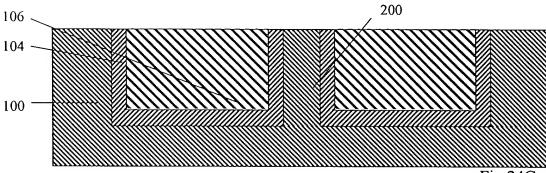


Fig.24C

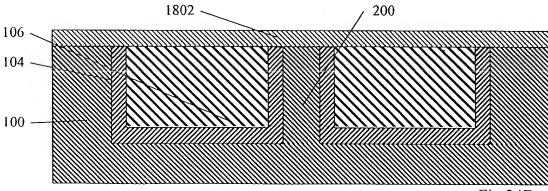
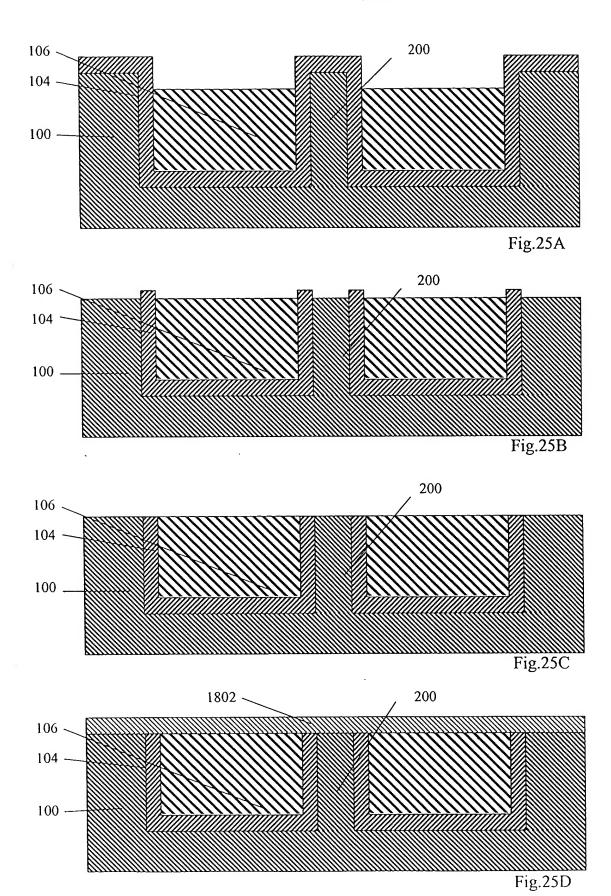


Fig.24D

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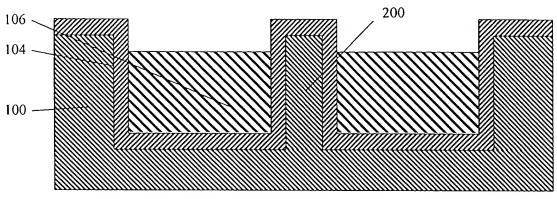
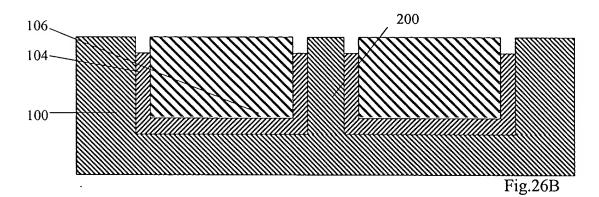
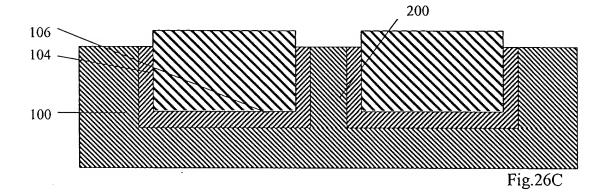


Fig.26A





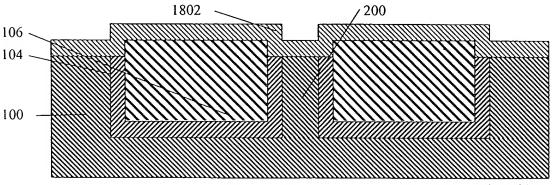


Fig.26D

Title: ELECTROPOLISHING METAL LAYERS ON WAFERS HAVING TRENCHES OR VIAS WITH DUMMY STRUCTURES

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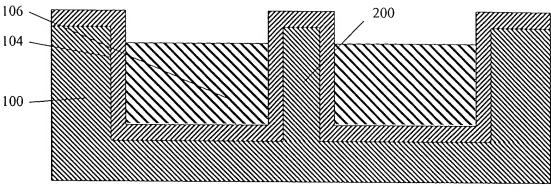


Fig.27A

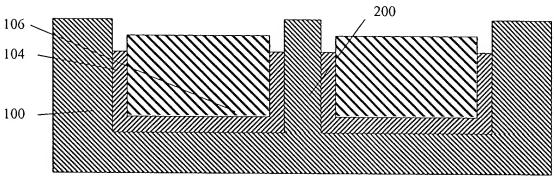


Fig.27B

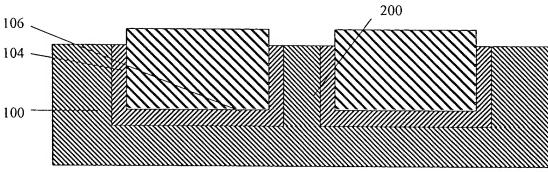


Fig.27C

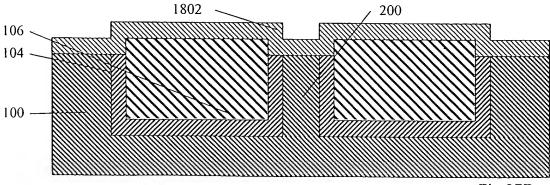


Fig.27D